APPLICA	BLE STAN	DARD									
Operating ter range		perature	• -55 °C to 85 °C S		Stora	Inorating or storage		-1	0°C TO 50°C(packed	d conc	lition)
RATING	Voltage Current		30V AC / D	30V AC / DC Ope				Relative humidity 90 %MAX(no			ot dewed)
			0.20 A	Appli			able		t=0.2±0.02mm, gold p	olating	l
			SPEC	CIFICA	IOIT	NS					
IT	EM		TEST METHOD				RE	QUI	REMENTS	QT	АТ
CONSTR	UCTION									•	
General exar	mination	Visually a	and by measuring instrumer	nt.			ling to drav	ving.		×	×
Marking		Confirmed	d visually.			(note 1,2)				×	×
ELECTR	ICAL CHA										
Voltage proof		90 V AC for 1 min.			No flashover or breakdown.				×	×	
Insulation res	sistance	100 V DC.				50 MΩ MIN.				×	×
Contact resis	stance	AC 20 mV MAX , 1 mA .				200 ms	Ω ΜΑΧ.			×	×
					including fpc,ffc bulk resistance (L=8mm)						
MECHAN	IICAL CHA	RACTE	RISTICS							-	
Vibration		Frequency 10 to 55 Hz, half amplitude				① No electrical discontinuity of 1 μs.				×	—
Observation		0.75 mm, for 10 cycles in 3 axial directions. 981 m/s ² , duration of pulse 6 ms				② Contact resistance: 200 mΩ MAX.					
Shock			, duration of pulse 6 ms in 3 both axial directions.			③ No	damage, c	rack	and looseness of parts.	×	-
Mechanical o	operation	10times insertions and extractions.				① Contact resistance: 200 mΩ MAX.				×	<u> </u>
							2 No damage, crack and looseness of parts.				
FPC retentio	n force		by applicable fpc. s of fpc shall be t=0.20mm	at initial or	ndition)	Direction of insertion: 1.98 N MIN (note 3)			×	_	
ENVIRO	NMENTAL		ACTERISTICS	at initial of	idition.,						
Corrosion sa		Exposed at 35±2 °C, 5 % salt water spray for 96 h.			① Contact resistance: 200 mΩ MAX.			×	Ι_		
					② No damage, crack and looseness of parts.						
						_			rosion which affects to		
Rapid chang	e of	Temperature-55→+15To+35→+85→+15To+35°C			operation of connector. (1) Contact resistance: 200 mΩ MAX.				×	+_	
temperature		Time $30 \rightarrow 2 \text{ To } 3 \rightarrow 30 \rightarrow 2 \text{ To } 3 \text{ min}$			② Insulation resistance: 50 M Ω MIN.				^		
			Under 5 cycles.				③ No damage, crack and looseness of parts.				
Damp heat (steady state	<i>.</i>)	Exposed at 40±2 °C, Relative humidity 90 to 95 %, 96 h.								×	-
Damp heat,c	•	- 1	at -10 to +65 °C,			① Cor	ntact resist	ance	: 200 mΩ MAX.	×	+_
	•	Relative humidity 90 to 96 %, 10 cycles, total 240 h.			 ② Insulation resistance: 1 MΩ MIN. (at high humidity) ③ Insulation resistance: 50 MΩ MIN. (at dry) 						
					No damage, crack and looseness of parts.						
Dry heat		Exposed	posed at 85±2 °C, 96 h.			① Contact resistance: 200 mΩ MAX.				×	_
Cold		Exposed	xposed at -55±3°C, 96 h.			② No damage, crack and looseness of parts.				×	_
Sulphur dioxide		Exposed at 40±2 °C,				 Contact resistance: 200 mΩ MAX. No damage, crack and looseness of parts. No evidence of corrosion which affects to 				×	-
Hydrogen sulphide		Relative humidity 80±5% 25±5 ppm for 96 h.									
		Exposed at 40±2 °C,			_	eration of co			×	+-	
		Relative I	numidity 80±5%,								
			ppm for 96 h.								
COUN	T DE	SCRIPTIC	ON OF REVISIONS		DESIG	NED			CHECKED	DA	TE
Z N REMARK							APPROV	ED	NE MIVAZAVI	16.0	11 10
IXEIVI/AIXIX							CHECKE		NF. MIYAZAKI HS. SAKAMOTO	16. C	
							DESIGNE	_	SI. MIZUSAWA	16.0	
Unless otherwise specified, re			efer to IEC 60512.				DRAWN		SI. MIZUSAWA	16.0	
•						FI 0 007570					
Note QT:Qualification Test AT:Assurance Test								158M-7S-0, 25SHW	U-U(J	
1			CONTOCTION ON LED			0.500.0044.0.00			Δ	1/2	
HIK FORM HD0011-2-1		OSE ELECTRIC CO., LTD. CODE			NO. 0L000-3011-0-00			<u> </u>	1/2		

SPECIFICATIONS							
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ			
Solderability	Soldered at solder temperature, 245±3°C for immersion duration, 3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	_			
Resistance to soldering heat	1) Reflow soldering: peak tmp. 250 °C MAX. reflow tmp. over 230 °C within 60 sec. 2) Soldering irons: tmp. 350±10 °C for 5±1 sec.	No deformation of case of excessive looseness of the terminals. (<i>note 4</i>)	×	_			

(note1)

This connector is back flip lock type, and top/bottom both contact points are available.

(note2)

Do not close the actuator before inserting fpc even after the connector is mounted onto a pcb.

Closing the actuator without fpc could make the contact gap smaller, which increases the fpc insertion force.

(note3)

Stabilize the fpc to pcb or something fixed, if pull-up or pull-down force is exepected to be applied to the fpc.

(note4)

Blisters which may be generated on the housing do not affect product performance.

Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWIN	IG NO.	ELC-367578-00-00			
H	HS SPECIFICATION SHEET		PART NO.	PART NO. FH58M-7S-0. 25SHW				
		HIROSE ELECTRIC CO., LTD.	CODE NO	CL580	-3811-0-00	Δ	2/2	